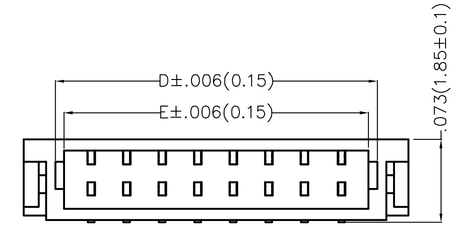
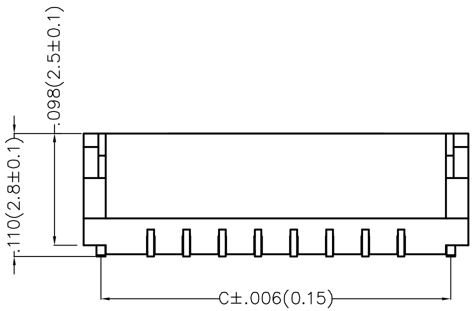
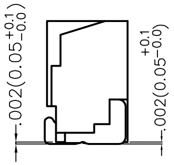
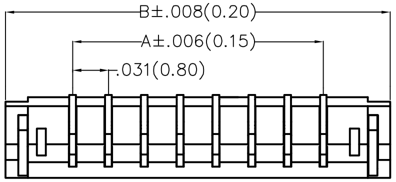
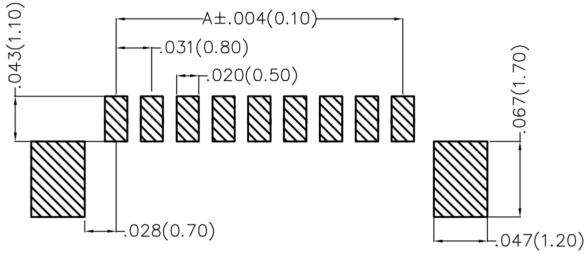
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Structural and material changes	15/APR/20	KATE	CHERRY
2		Structural and Size changes	25/MAR/22	MATT	CHERRY











Recommended P.C.Board Layout

General tolerances: ±.002(0.05)

SPECIFICATIONS

Electrical
- Current Rating: 0.5A AC(rms)/DC
- Voltage Rating: 30V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 100 MΩ Min
- Withstanding Voltage: 200V AC r.m.s
- Temperature Range—Operating: −40°C~+105°C

Material and Plating
- Housing: LCP (UL 94V—0)
- Contact: Phosphor bronze/ Gold flash or Tin plated
- Solder Tab: Brass/ Gold flash or Tin plated

Ordering Information

FWF	080	01	—	S	XX	S	X	3	W5	M
1	**2**	**3**		**4**	**5**	**6**	**7**	**8**	**9**	**10**

No.	Item	Option
1	Category	FWF—Wafer
2	Series Number	080—Pitch0.8mm
3	Distinction No.	01
4	Row Option	S—Single Row
5	Circuits	XX
6	Entry Angle	S—180° Vertical
7	Plating	1—Gold Plated 2—Tin Plated
8	Material—Resin	3—LCP
9	Color—Resin	W5—Natural
10	Packaging	M—Reel

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF08001—SXXSX3W5M	ITEM NO. FWF08001
DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.°±5°	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 0.8mm 180° Vertical (SMT)	REV 2	SHEET NO. 1/3
	X.X±.008(0.20)	.X°±2°				
SCALE 5:1 / SIZE A4	X.XX±.006(0.15)	.XX°±1°	DRAWN BY CHERRY	DATE 28/JUN/13		
	X.XXX±.004(0.10)	.XXX°±0.5°				

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REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part No.	Dimensions(in/mm)				
		A	B	C	D	E
2	FWF08001–S02SX3W5M	.031(0.80)	.150(3.80)	.118(3.00)	.094(2.40)	.079(2.00)
3	FWF08001–S03SX3W5M	.063(1.60)	.181(4.80)	.150(3.80)	.126(3.20)	.030(2.80)
4	FWF08001–S04SX3W5M	.094(2.40)	.213(5.40)	.181(4.60)	.157(4.00)	.142(3.60)
5	FWF08001–S05SX3W5M	.126(3.20)	.244(6.20)	.213(5.40)	.189(4.80)	.173(4.40)
6	FWF08001–S06SX3W5M	.157(4.00)	.276(7.00)	.244(6.20)	.220(5.60)	.205(5.20)
7	FWF08001–S07SX3W5M	.189(4.80)	.3.07(7.80)	.276(7.00)	.252(6.40)	.236(6.00)
8	FWF08001–S08SX3W5M	.220(5.60)	.338(8.60)	.307(7.80)	.283(7.20)	.269(6.80)
9	FWF08001–S09SX3W5M	.252(6.40)	.370(9.40)	.339(8.60)	.315(8.00)	.299(7.60)
10	FWF08001–S10SX3W5M	.283(7.20)	.402(10.20)	.370(9.40)	.345(8.80)	.331(8.40)
12	FWF08001–S12SX3W5M	.346(8.80)	.465(11.80)	.433(11.00)	.409(10.40)	.394(10.00)
16	FWF08001–S16SX3W5M	.472(12.00)	.591(15.00)	.559(14.20)	.535(13.60)	.520(13.20)
20	FWF08001–S20SX3W5M	.598(15.20)	.717(18.20)	.685(17.40)	.661(16.80)	.646(16.40)

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF08001–SXXSX3W5M
	X.±.012(0.30)	X.°±5°	CHECKED BY JACOB	DATE 28/JUN/13	ITEM NO. FWF08001
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X°±2°			TITLE Wire to Board (Wafer) Pitch 0.8mm 180° Vertical (SMT)
SCALE 5:1	X.XX±.006(0.15)	.XX°±1°	DRAWN BY CHERRY	DATE 28/JUN/13	REV 2
SIZE A4	X.XXX±.004(0.10)	.XXX°±0.5°			SHEET NO. 2/3

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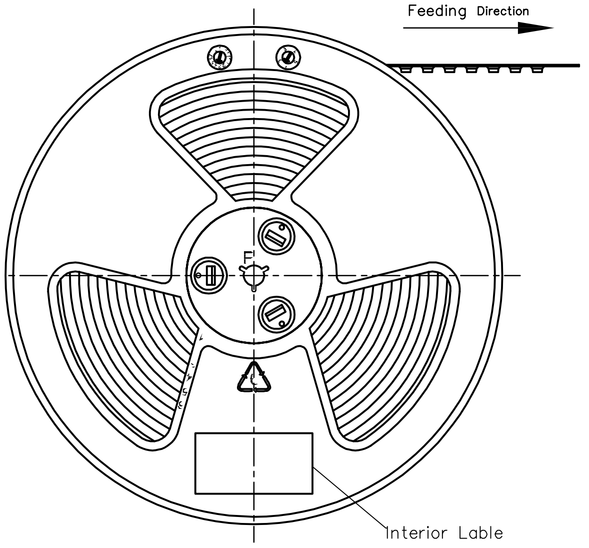
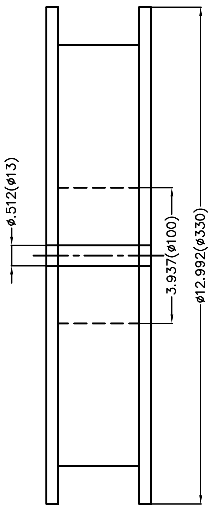
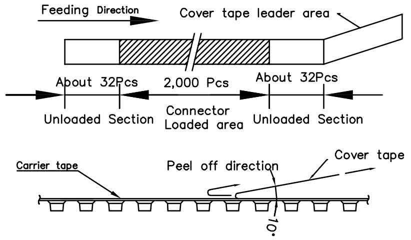
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

1. 10 sprocket hole cumulative tolerance±0.2
2. Carrier camber is within 1.0mm in 250mm
3. Materlat: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Peel off force of cover tape&carrier tape: 20g~130g(0.2N~1.3N)
6. Component load per 13" reel: 2,000 pcs

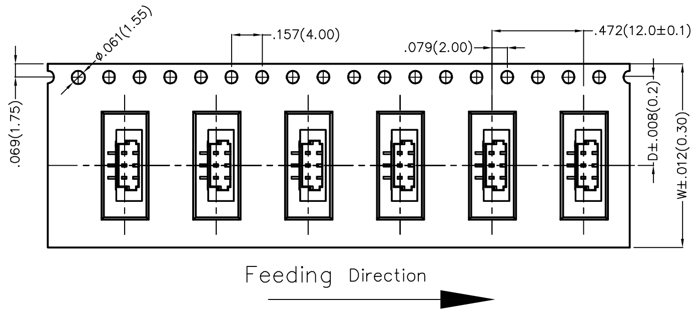


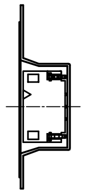


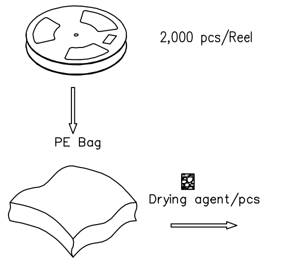


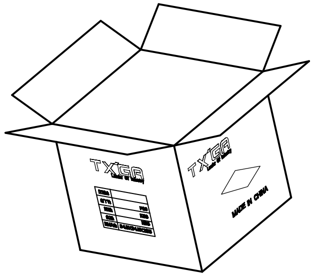
Circuits (n)	Dimensions(in/mm)	
	D	W
2	.295(7.50)	.630(16.00)
3	.295(7.50)	.630(16.00)
4	.295(7.50)	.630(16.00)
5	.295(7.50)	.630(16.00)
6	.295(7.50)	.630(16.00)
7	.295(7.50)	.630(16.00)

Circuits (n)	Dimensions(in/mm)	
	D	W
8	.295(7.50)	.630(16.00)
9	.295(7.50)	.630(16.00)
10	.453(11.50)	.945(24.00)
12	.453(11.50)	.945(24.00)
16	.453(11.50)	.945(24.00)
20	.453(11.50)	.945(24.00)









THIRD ANGLE PROJECTION

DESIGN UNITS
Inch (metric)

SCALE 5:1
SIZE A4

GENERAL TOLERANCES (UNLESS SPECIFIED)	
X.±.012(0.30)	X.°±5°
X.X±.008(0.20)	.X°±2°
X.XX±.006(0.15)	.XX°±1°
X.XXX±.004(0.10)	.XXX°±0.5°

APPROVE BY	FRANK	DATE 28/JUN/13
CHECKED BY	JACOB	DATE 28/JUN/13
DRAWN BY	CHERRY	DATE 28/JUN/13

PART NO.
FWF08001-SXXSX3W5M

ITEM NO.
FWF08001

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TITLE
Wire to Board (Wafer)
Pitch 0.8mm 180° Vertical (SMT)

REV 2
SHEET NO. 3/3